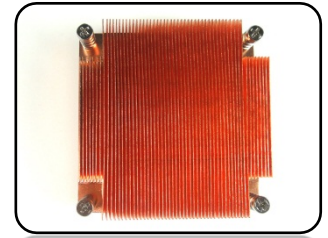


All copper, Skive Fin Technology



Top View



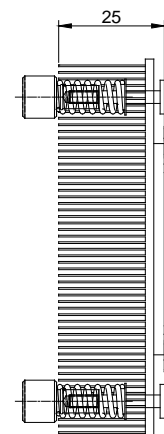
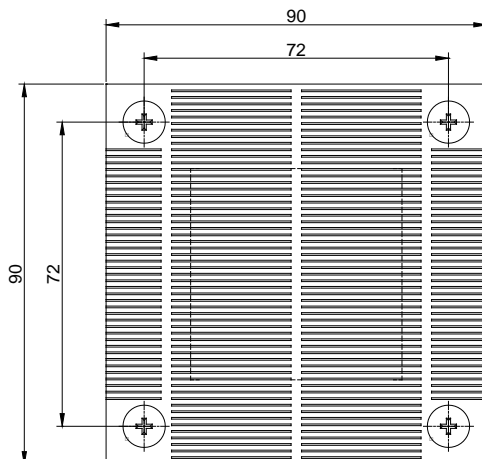
Backplane

Product Specification

Application Socket	Intel LGA 1366 (Square Type)
Heat Sink Dimension	90mm X 90mm X 24mm
Heat Sink Material	Copper
Weight (g)	500
CPU Support	Intel® Xeon® Processor 3000 Sequence X3230 ~X3380 3040 ~ 3070 E3110 , E3120 , L3110

Features:

- Max TDP 95W(Up To System Fan)
- All Copper Provides Faster Heat Dissipation Rate
- Design For 1U Server
- For Blade Server Design



Unit : mm